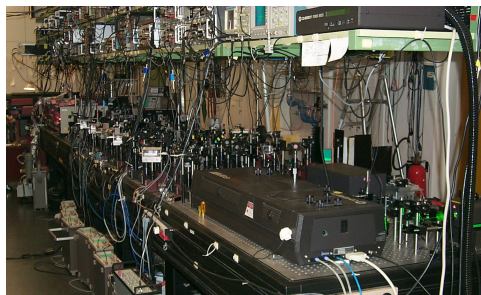




**Low loss  
Photonic Integration:  
SWaP advantages for  
Space**

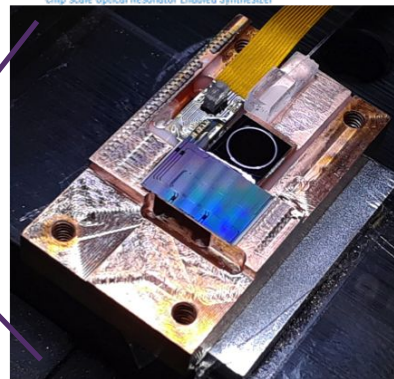
# Size, Weight and Power (SWaP) reduction



4 m<sup>3</sup>



1 m<sup>3</sup>



1 cm<sup>3</sup>

- ✓ Less complexity
- ✓ Power efficient
- ✓ Small size
- ✓ No movable parts

1998

2008

2019

# Benefits of Silicon Nitride

Large transparency window: 400 – 4'000 nm

*Reference Silicon: 1'100 – 4'000 nm*

Low propagation loss: < 1dB/m

*Reference Silicon: 50-1000 dB/m*

High optical power: > 5 W per waveguide ( $10^9$  W/cm<sup>2</sup>)

*Reference Silicon: 0.1 W per waveguide*

Scalable to volume

*Non exotic material*

Radiation hardness proven

*Space compatible*



Telecom



Data Center



AR / VR



Wearables



BioSensing



LiDAR



Space



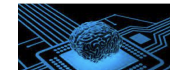
Quantum Computing



Atomic Clocks



Astronomy



Neurom. Computing



5G



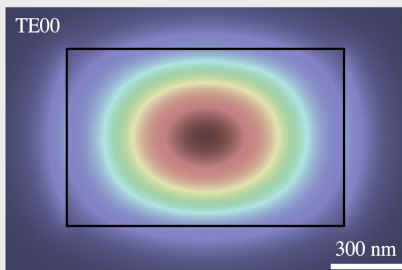
Quantum Crypto



Next big thing

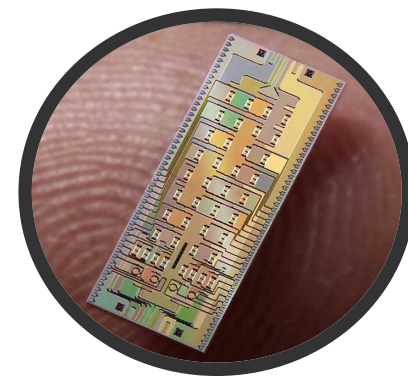
*required for many applications*

## Thick SiN – the game changer



### 90% of the light is confined

- Low propagation loss
- Small chip size
- Dispersion engineering
- High Power, VIS to IR



A base to build on  
**Versatile Platform**



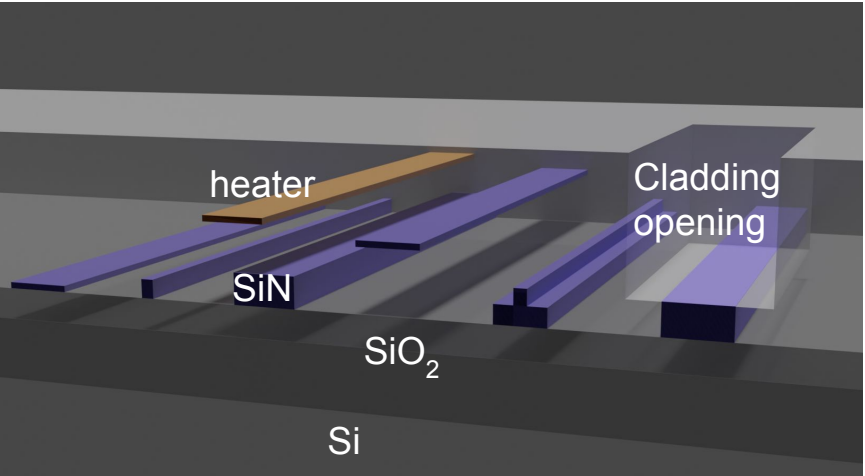
3+ thicknesses      10+ process modules      Extensive PDK

800 nm

350 nm

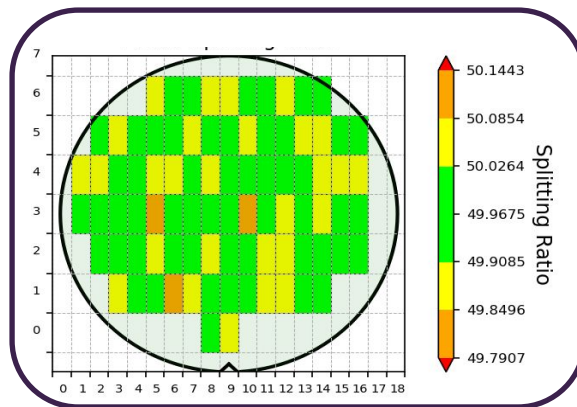
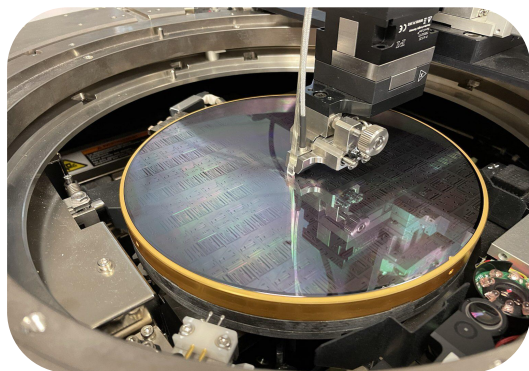
150 nm

custom



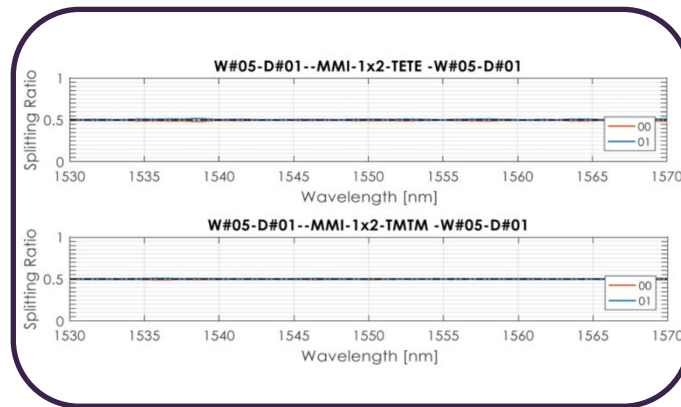
High throughput optical testing

# PDK Development and Quality Control



Reproducible

TE / TM



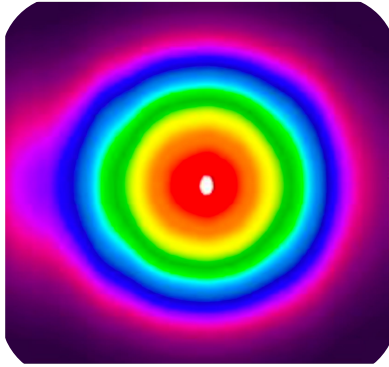
Broadband

LIGEN<sup>TEC</sup> interposer platform

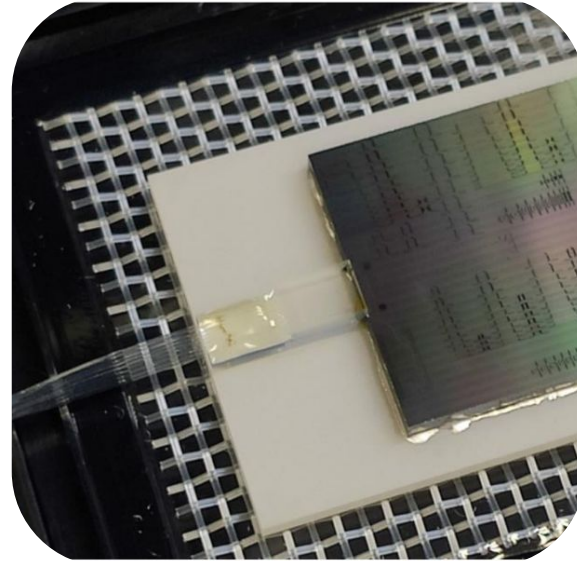
## High performance optical I/O



*Proven track-record in development of efficient optical I/O interfaces*



|                       |      |
|-----------------------|------|
| MFD [ $\mu\text{m}$ ] | 9.7  |
| $M^2$                 | 1.06 |



# Seamless journey from Idea to Volumes

## Entry: R&D & Prototyping

*Open access, low barrier*

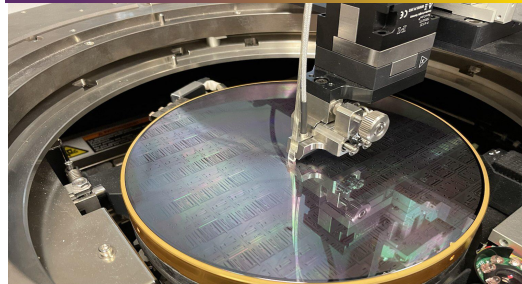


### Fast prototyping

- Established technology
- Fixed layer stack
- Extensive PDK
- **Regular MPW runs**
- Custom runs
- Design / layout support
- Characterization
- Packaging support

## Optimize: Development

*High flexibility & competence*



### Custom PIC Developments

- Engineering studies
  - Layer stack adaptation
  - Custom integrations
- ### Ligentec Labs
- Early technology access

## Manufacturing: Supply

*Quality and guarantee*



### Pilot Fabrication

- Pilot and niche quantities

### Volume Fabrication

- Large volumes
- High-capacity wafer fab
- Fully automated testing
- Automotive quality system



The next step – enhance the SiN PIC platform

## SiN – The platform for heterogeneous integration



Use SiN as base platform for general circuitry

- Comprehensive PDK
- Standard I/Os
- Scalable to volume

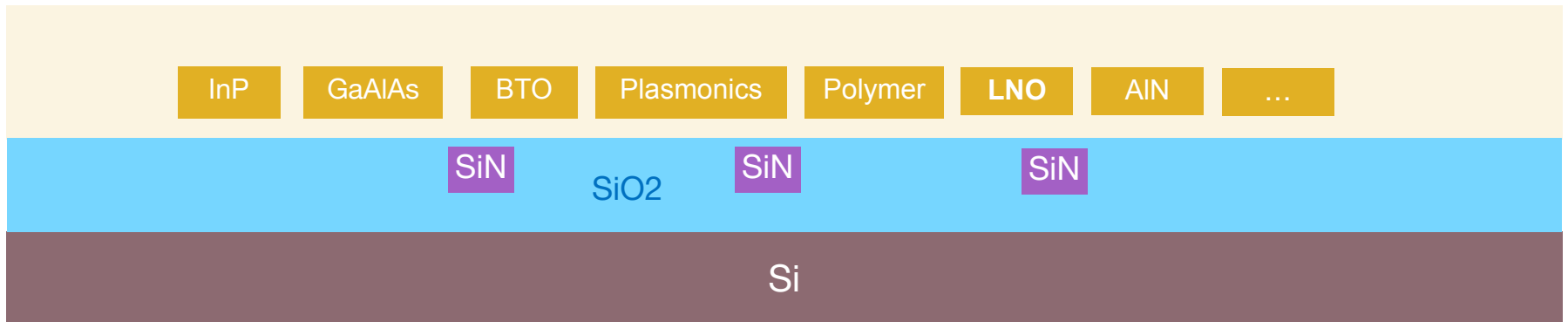
Add materials as required by application

OPTICA

**100 GHz bandwidth, 1 volt integrated electro-optic Mach-Zehnder modulator at near-IR wavelengths**

FORREST VALDEZ, VIPHRETUO MERE, AND SHAYAN MOOKHERJEA\*

University of California, San Diego, Department of Electrical and Computer Engineering, La Jolla, California 92093-0407, USA  
\*smookherja@ucsd.edu

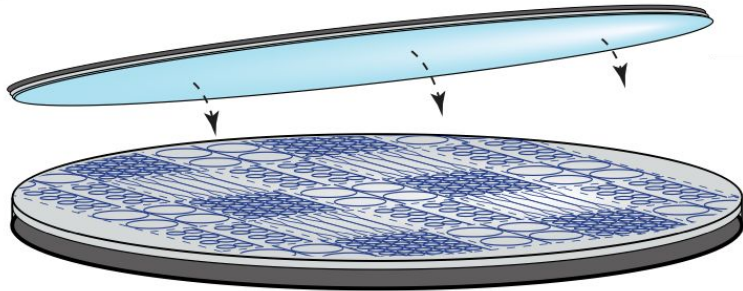


The next step – enhance the SiN PIC platform

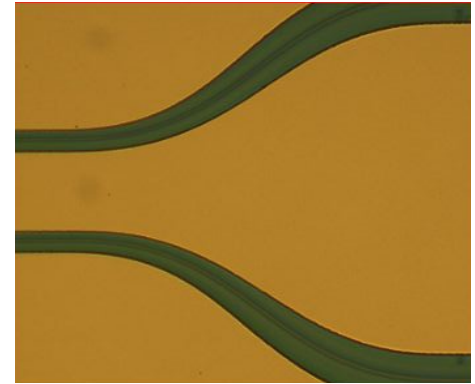
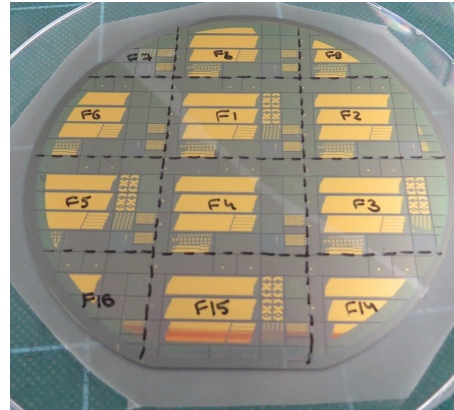
## Heterogeneous integration of modulators

LIGENTEC

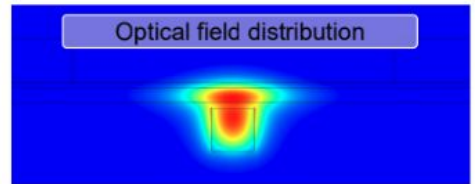
LiNbO<sub>3</sub>



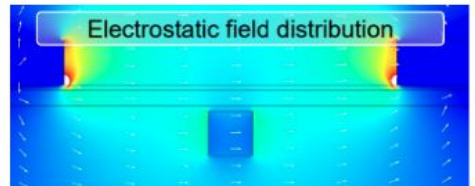
SiN



Optical field distribution

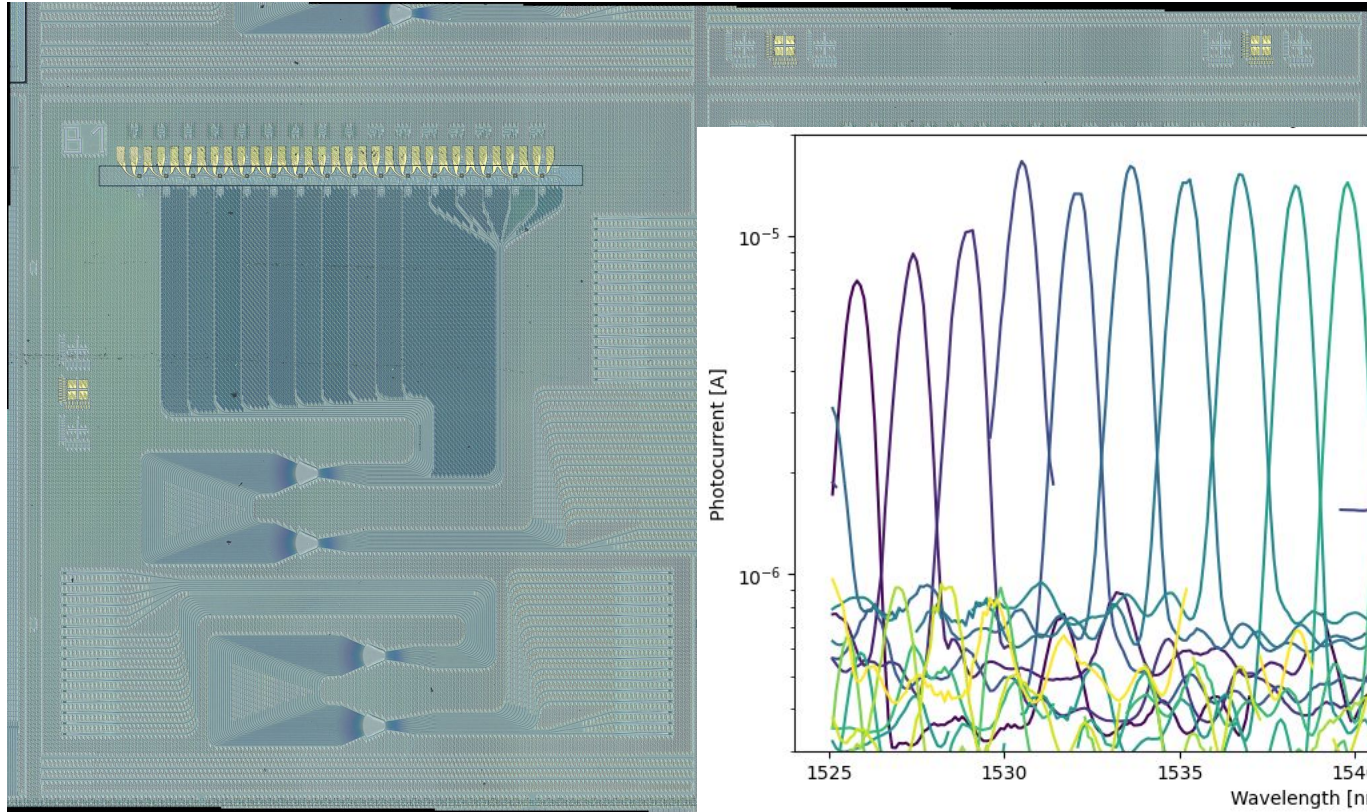


Electrostatic field distribution



The next step – enhance the SiN PIC platform

## Heterogeneous integration of photodiodes

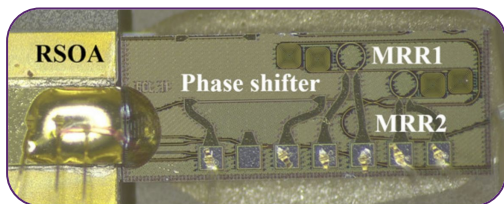
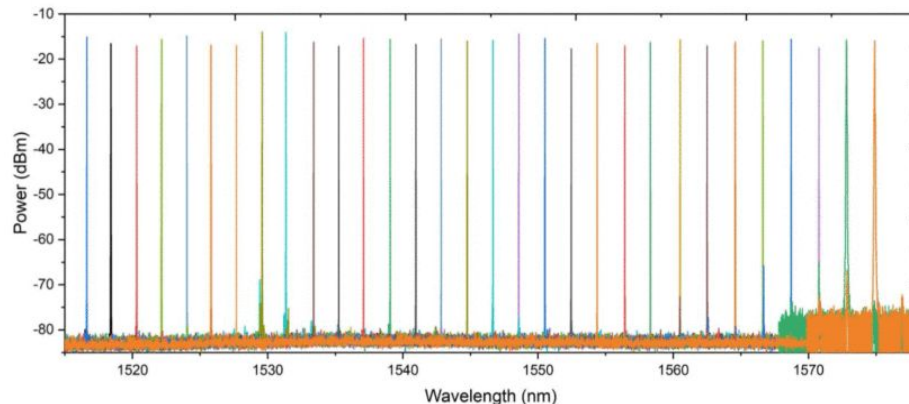
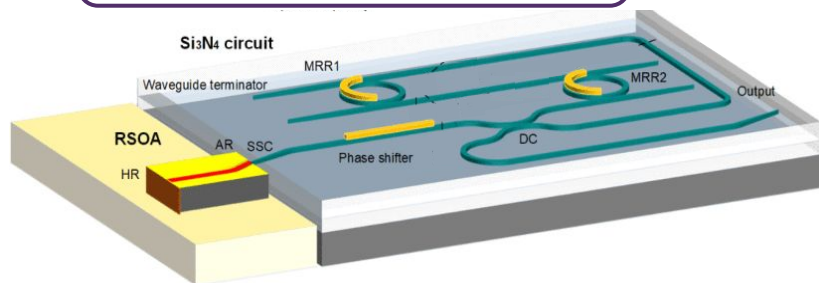


## The next step – enhance the SiN PIC platform

# Hybrid integration of lasers



**LIGENTEC design, layout and fabrication capability**



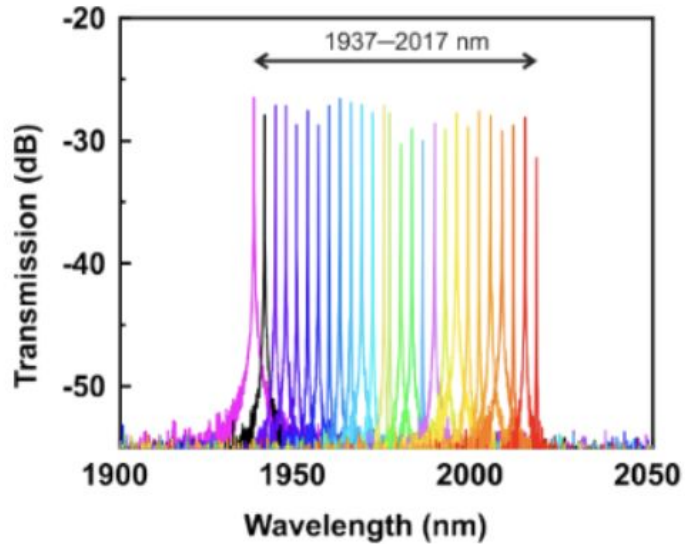
### Narrow Linewidth External Cavity Lasers

**Linewidth: <3kHz**  
**SMSR: -70dB**

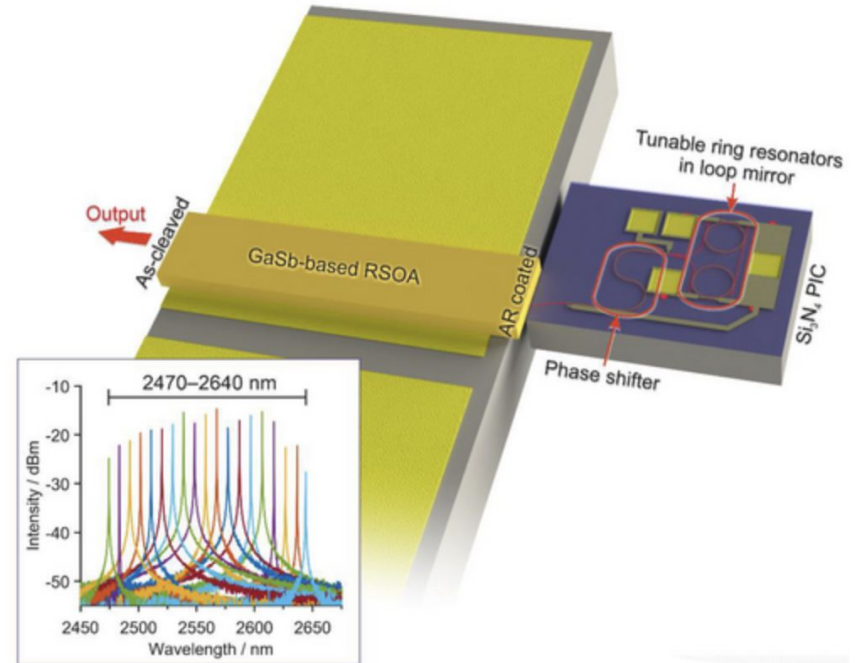
**Max power: 34mW**  
**Tuning: 58.5nm**

The next step – enhance the SiN PIC platform

## GaSb/Si<sub>3</sub>N<sub>4</sub> hybrid laser at 2 μm and 2.5 μm



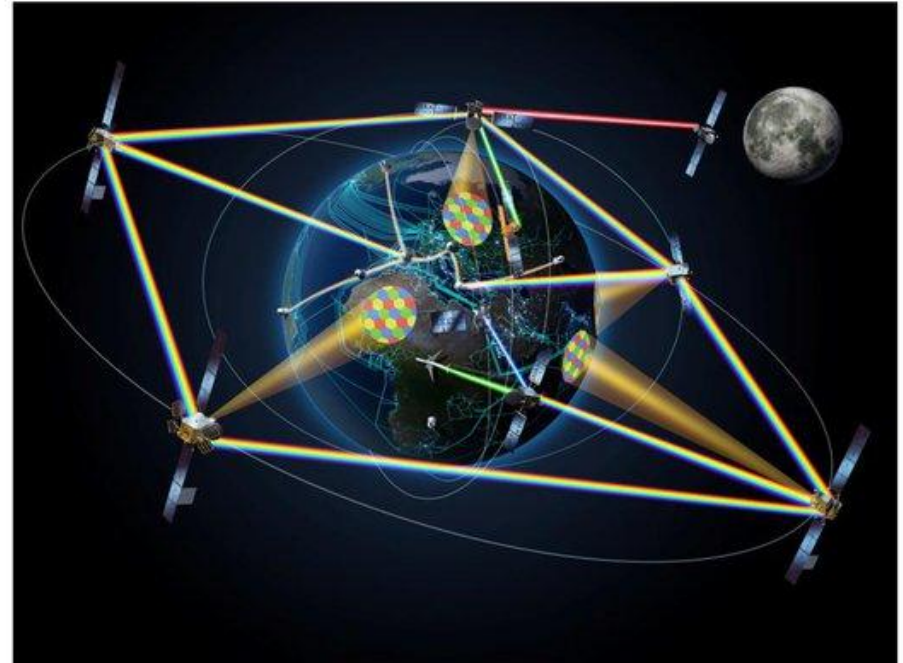
Zia et al., arXiv 2211.02135 (2022)



Ojanen et al., Laser&Photonics Review (2023)



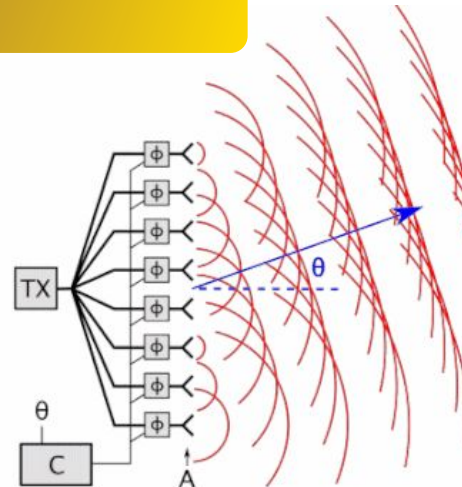
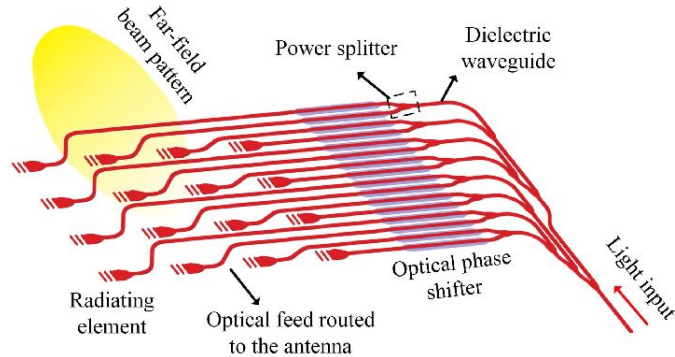
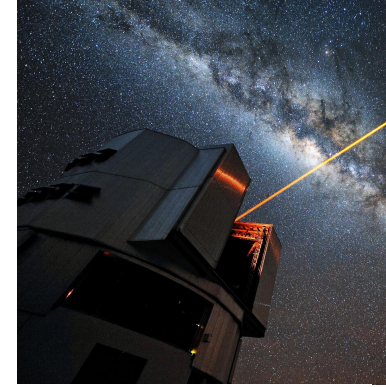
Artist Impression of HydRON Vision of an all optical space network integrated into terrestrial network infrastructures. **Image credit: ESA**



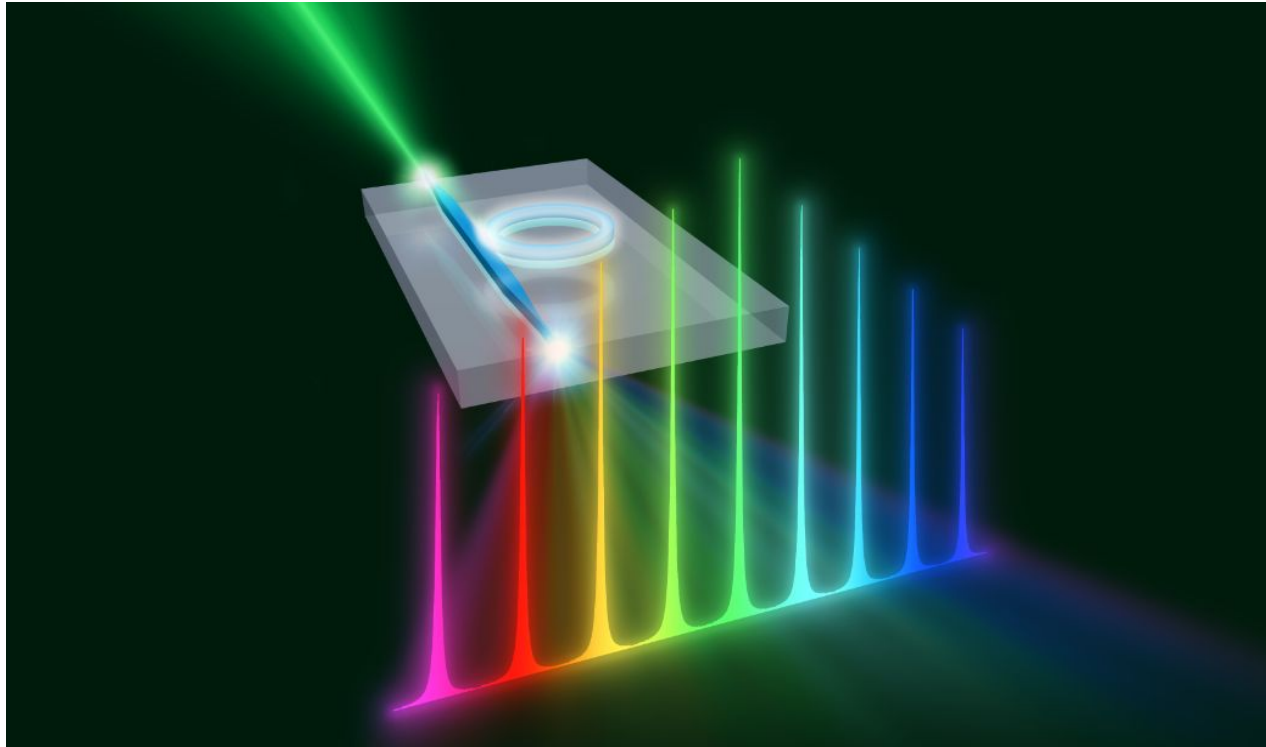
## Space Adaptive Photonics Phased Array IR Feeder Link



- Need for more bandwidth (intra-satellite and satellite to earth)
- High power light propagation
- Low loss optical phase shifter



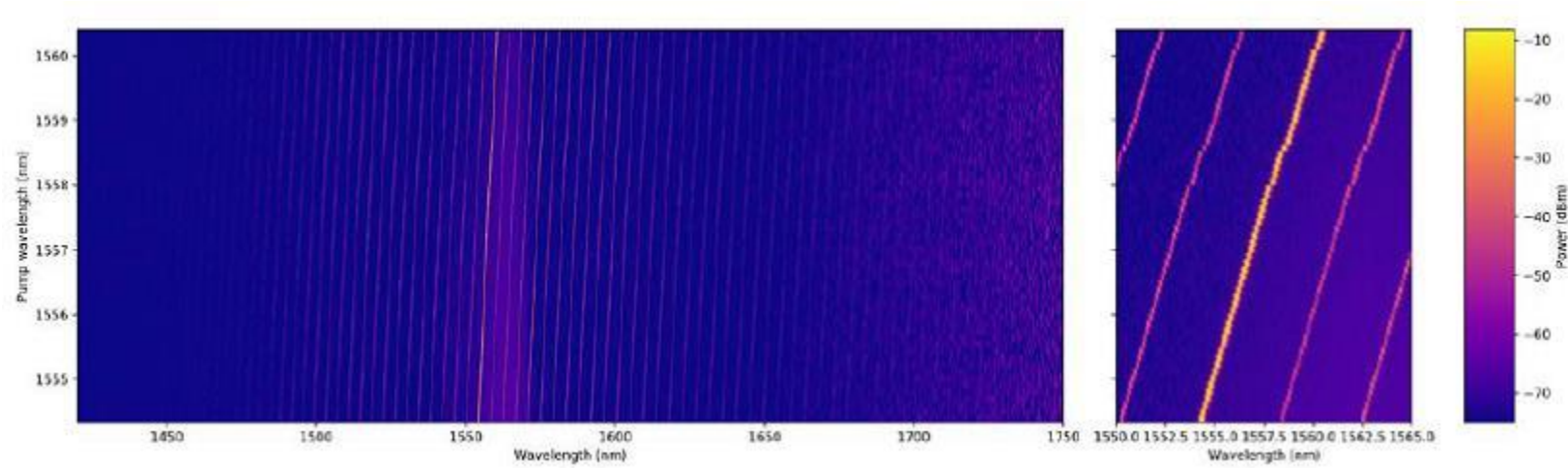
## Generation of on chip frequency comb



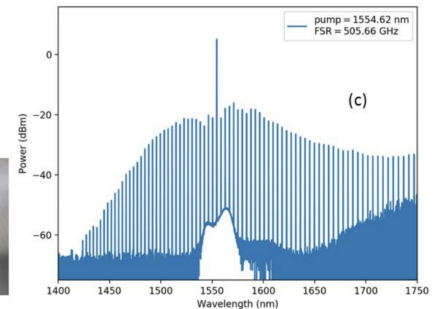
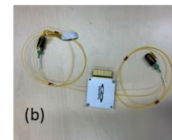
Frequency comb  
generation on chip



# Space Spectrograph Design to Calibration



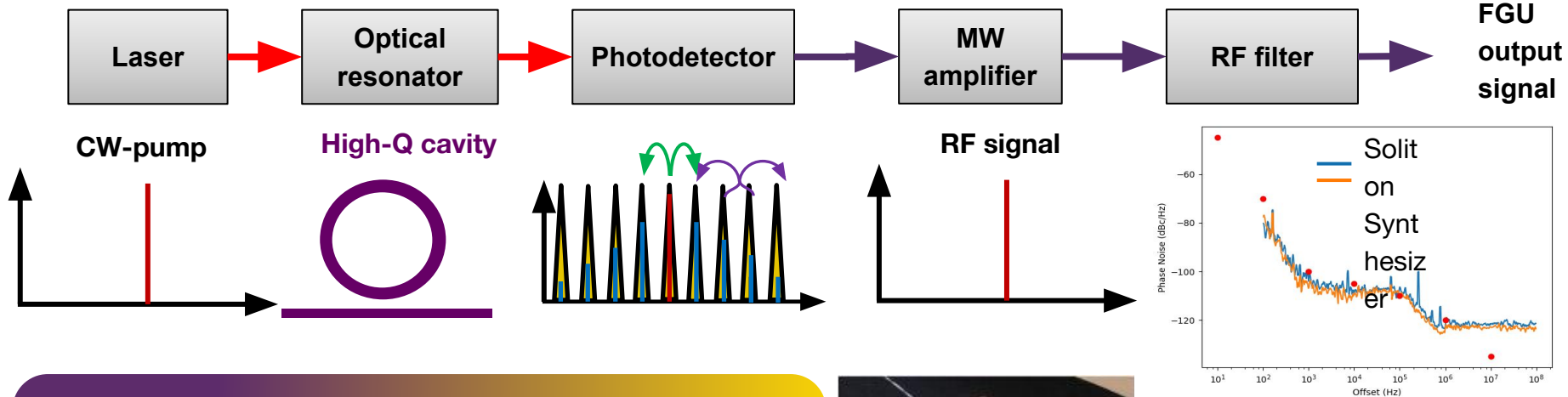
Full 500GHz tuning of a ring resonator



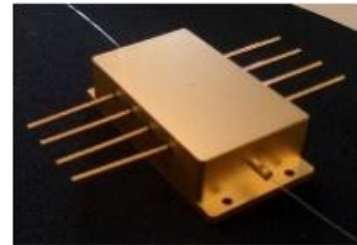
# FGU: RF Frequency Generation Unit for Telecommunication Payloads

LIGENTEC

Optical signal  
Electrical signal

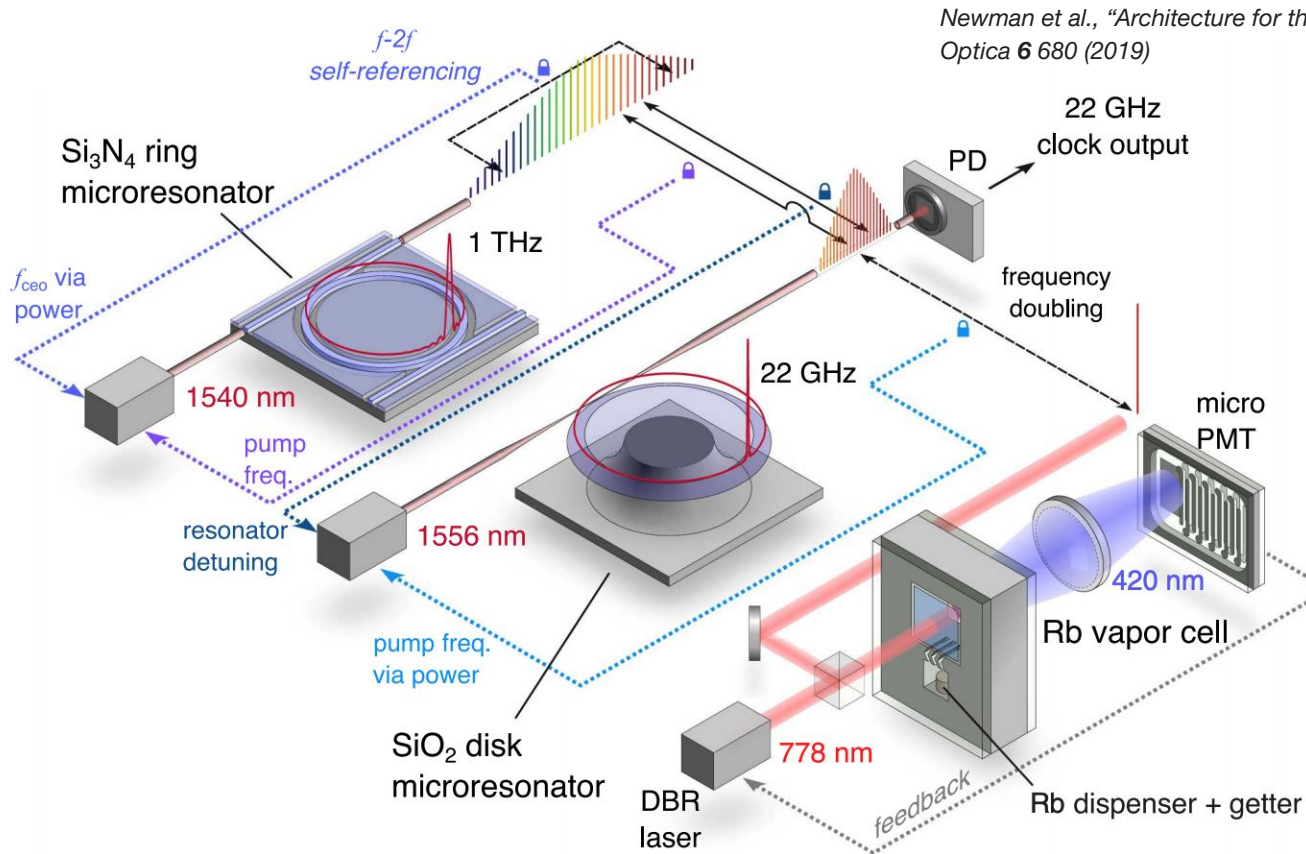


complex modulation and multiple frequency conversion require:  
ultralow phase noise reference LO (8-10GHz)



Pulsed soliton regime:  
no excess phase noise

# Building blocks for optical atomic clocks



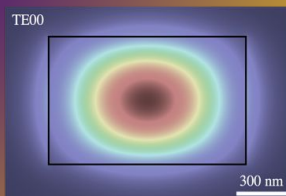
Newman et al., "Architecture for the photonic integration of an optical atomic clock",  
*Optica* **6** 680 (2019)

## Summary

# Low Loss SiN - Platform Overview



## Low loss waveguides



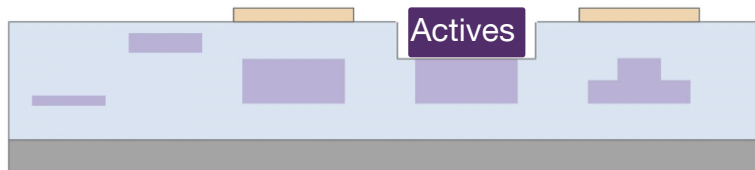
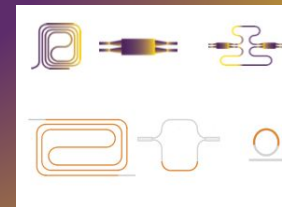
**MPW / Dedicated runs**

**Short turn around**

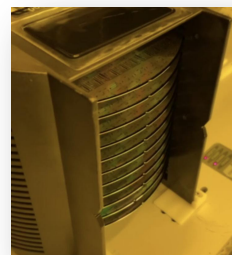
**Flexible R&D line**

**Volume line**

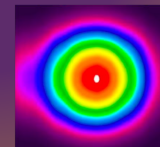
## Extensive PDK



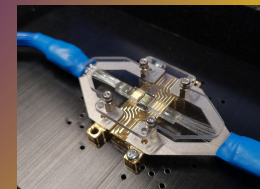
## Actives Integration



## Low loss optical I/O



MFD 9.7  
[ $\mu\text{m}$ ]  
 $M^2$  1.06



photonFab

This project has received funding from the European Union's Horizon 2020 research and innovation program under grant agreement #954530, #863322, #812818, #780537, #871658, #965124, #101070342, #101111896, and by BPI France. Co-funded by Innosuisse - Swiss Innovation Agency, and by the Swiss State Secretariat for Education, Research and Innovation (SERI)